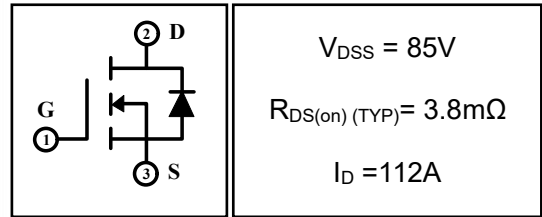


112A 85V N-channel Enhancement Mode Power MOSFET

1 Description

These N-channel enhancement mode power mosfets used advanced splite gate trench technology design, provided excellent Rdson and low gate charge. Which accords with the RoHS standard.

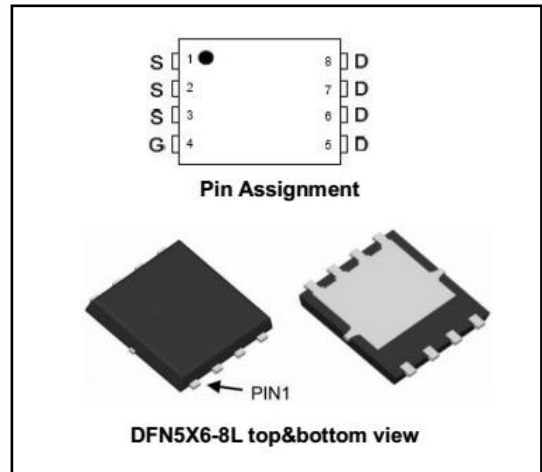


2 Features

- Fast switching
- Low on resistance
- Low gate charge
- High avalanche current
- Low reverse transfer capacitances
- 100% single pulse avalanche energy test
- 100% ΔV_{DS} test

3 Applications

- Synchronous rectification in SMPS
- Hard switching and high speed circuit
- Power tools
- UPS
- Motor control



4 Electrical Characteristics

4.1 Absolute Maximum Ratings (Tc=25°C, unless otherwise noted)

| Parameter | Symbol | Rating | Units |
|--|-------------------|-----------|-------|
| Drain-to-Source Voltage | V_{DS} | 85 | V |
| Gate-to-Source Voltage | V_{GS} | ± 20 | V |
| Continuous Drain Current | $T_C=25^\circ C$ | I_D | 112 |
| | $T_C=100^\circ C$ | | 78 |
| Pulsed Drain Current ⁽¹⁾ | I_{DM} | 448 | A |
| Single Pulse Avalanche Energy ⁽⁴⁾ | E_{AS} | 420 | mJ |
| Avalanche Current ⁽⁴⁾ | I_{AS} | 41 | A |
| Power Dissipation | $T_a=25^\circ C$ | P_{tot} | -- |
| | $T_C=25^\circ C$ | P_{tot} | 160 |
| Junction Temperature Range | T_j | -55 ~ 150 | °C |
| Storage Temperature Range | T_{stg} | -55 ~ 150 | °C |

4.2 Thermal Characteristics

| Parameter | Symbol | Rating | Units |
|---|------------|--------|-------|
| Thermal Resistance, Junction to Case-sink | R_{thJC} | 0.78 | °C/W |
| Thermal Resistance, Junction to Ambient | R_{thJA} | -- | °C/W |

4.3 Electrical Characteristics (T_c=25°C, unless otherwise noted)

| Parameter | Symbol | Test Condition | Value | | | Units |
|---|---------------------|--|-------|------|------|-------|
| | | | Min | Typ | Max | |
| Off Characteristics | | | | | | |
| Drain-to-Source Breakdown Voltage | BV _{DSS} | I _D =250μA, V _{GS} =0V | 85 | -- | -- | V |
| Drain-to-Source Leakage Current | I _{DSS} | V _{DS} =85V, V _{GS} =0V, T _C =25°C | -- | -- | 1 | μA |
| | | V _{DS} =85V, V _{GS} =0V, T _C =125°C | -- | -- | 100 | μA |
| Gate-to-Source Leakage Current | I _{GSS} | V _{GS} =±20V, V _{DS} =0V | -- | -- | ±100 | nA |
| On Characteristics | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} =V _{GS} , I _D =250μA | 2 | 3 | 4 | V |
| Drain-to-Source on-state Resistance | R _{DS(on)} | V _{GS} =10V, I _D =60A | -- | 3.8 | 4.6 | mΩ |
| Dynamic Characteristics | | | | | | |
| Input Capacitance | C _{iss} | V _{GS} =0V, V _{DS} =50V, f=1.0MHz | -- | 5690 | -- | pF |
| Output Capacitance | C _{oss} | | -- | 712 | -- | |
| Reverse Transfer Capacitance | C _{rss} | | -- | 271 | -- | |
| Gate Resisitance | R _G | V _{DD} =0V, V _{GS} =0V, F=1MHz | -- | 3.3 | -- | Ω |
| Switching Characteristics | | | | | | |
| Turn-on Delay Time | t _{d(on)} | I _D =70A, V _{DD} =40V, V _{GS} =10V, R _{GEN} =1.6Ω | -- | 23 | -- | nS |
| Turn-on Rise Time | t _r | | -- | 107 | -- | |
| Turn-off Delay Time | t _{d(off)} | | -- | 51 | -- | |
| Turn-off Fall Time | t _f | | -- | 103 | -- | |
| Total Gate Charge | Q _g | I _D =70A, V _{DD} =40V, V _{GS} =10V | -- | 78 | -- | nC |
| Gate-to-Source Charge | Q _{gs} | | -- | 36 | -- | |
| Gate-to-Drain("Miller") Charge | Q _{gd} | | -- | 13 | -- | |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage ⁽³⁾ | V _{SD} | V _{GS} =0V, I _S =60A | -- | 0.9 | 1.3 | V |
| Diode Forward Current | I _S | | -- | -- | 112 | A |
| Reverse Recovery Time ⁽³⁾ | t _{rr} | T _J =25°C, I _F =100A, di _F /dt=100A/μS, V _{GS} =0V | -- | 60 | -- | nS |
| Reverse Recovery Charge ⁽³⁾ | Q _{rr} | | -- | 61 | -- | nC |

Notes:

1: Repetitive rating, pulse width limited by maximum junction temperature.

2: Surface mounted on FR4 Board, t≤10sec.

3: Pulse width ≤ 300μs, duty cycle ≤ 2%.

4: L=0.5mH, I_D=41A, V_{DD}=50V, V_{GATE}=85V, Start T_J=25°C.

5 5 Typical characteristics diagrams

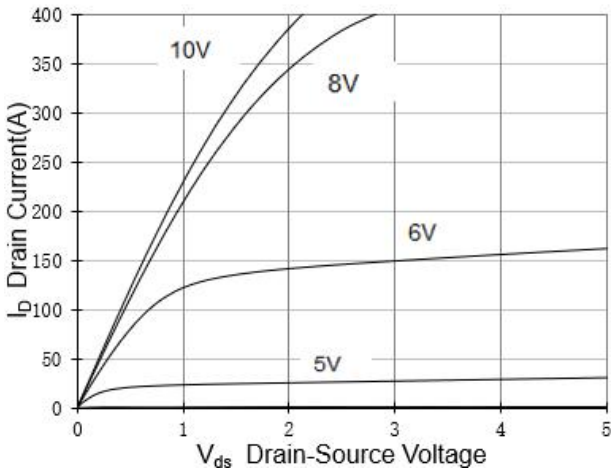


Figure 1 Output Characteristics

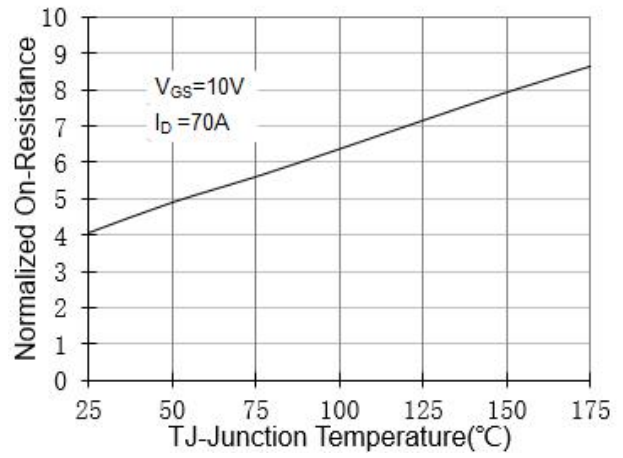


Figure 2 Rdson-Junction Temperature

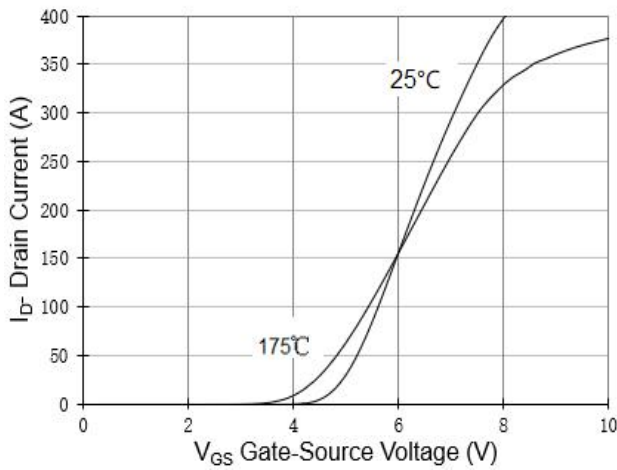


Figure 3 Transfer Characteristics

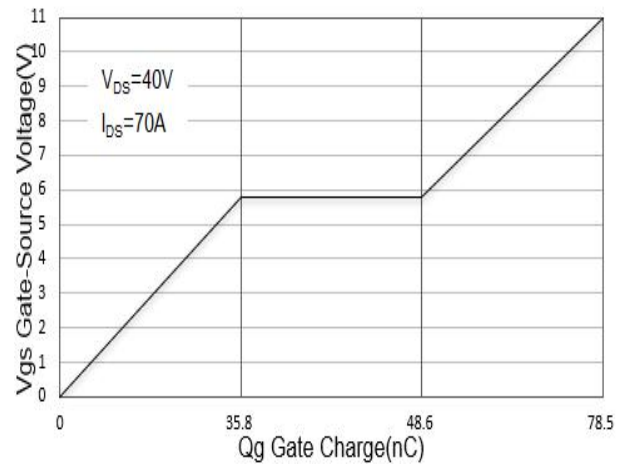


Figure 4 Gate Charge

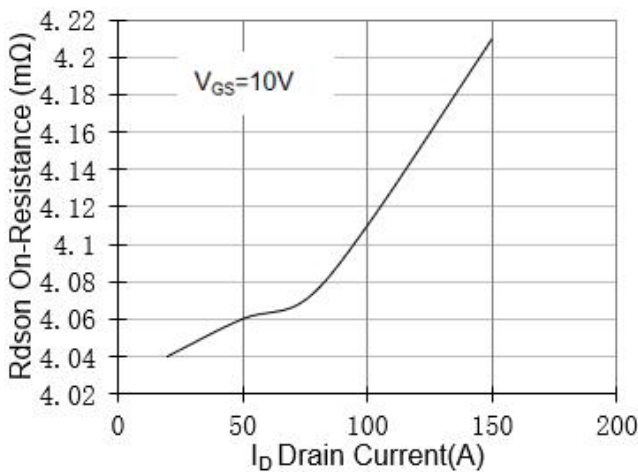


Figure 5 Rdson-Drain Current

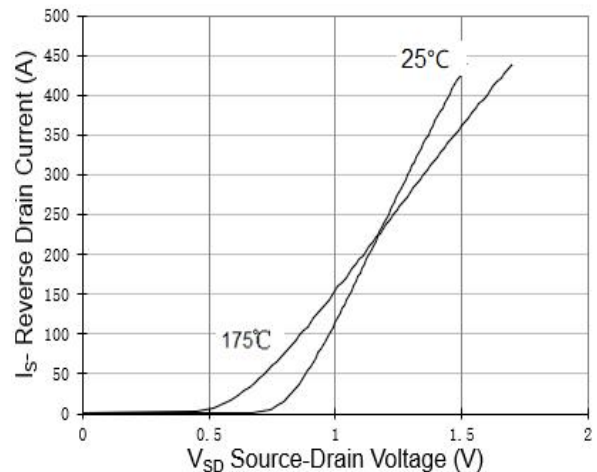


Figure 6 Source-Drain Diode Forward

5 Typical characteristics diagrams(continues)

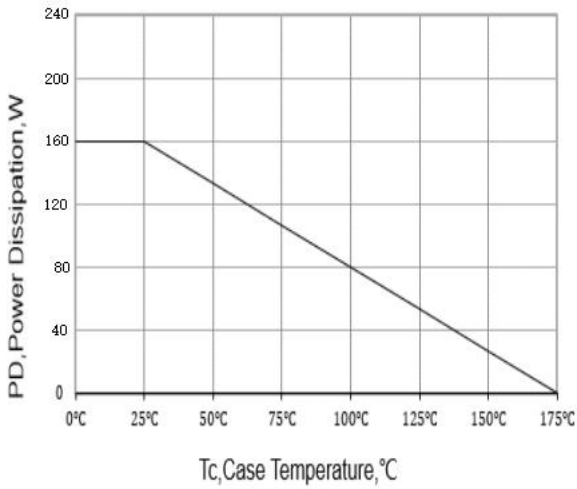


Figure 7 Power De-rating

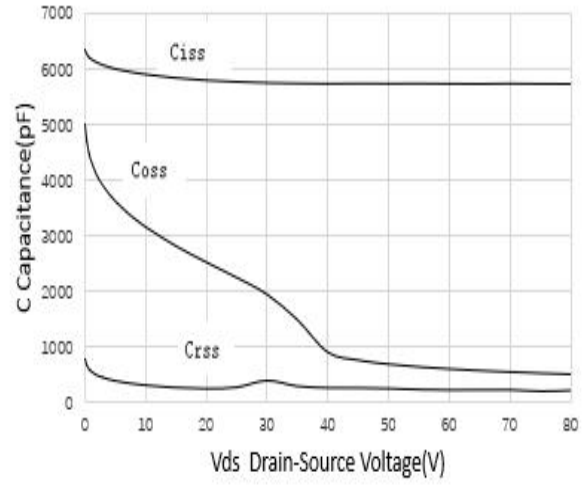


Figure 8 Capacitance vs Vds

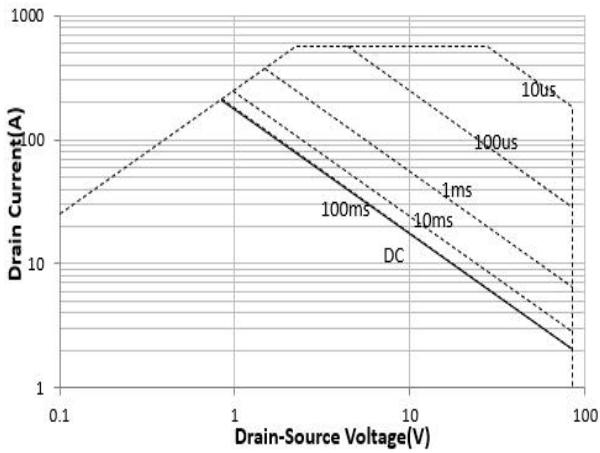


Figure 9 Safe Operation Area

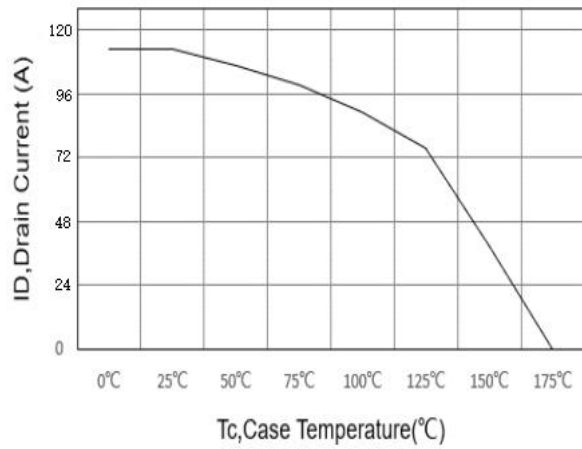
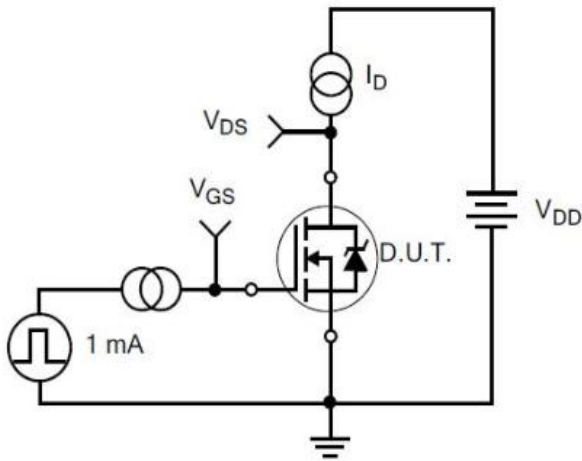
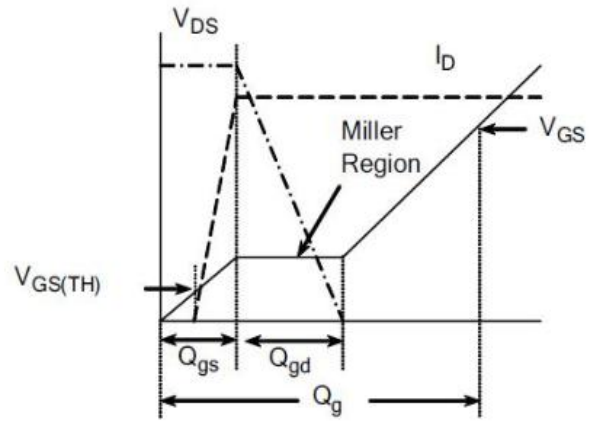


Figure 10 Current De-rating

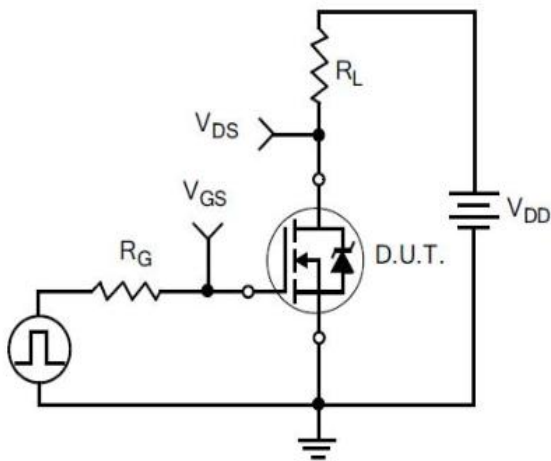
6 Typical Test Circuit and Waveform



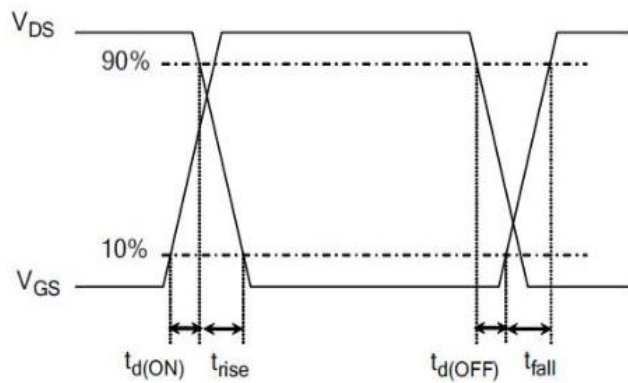
1) Gate Charge Test Circuit



2) Gate Charge Waveform

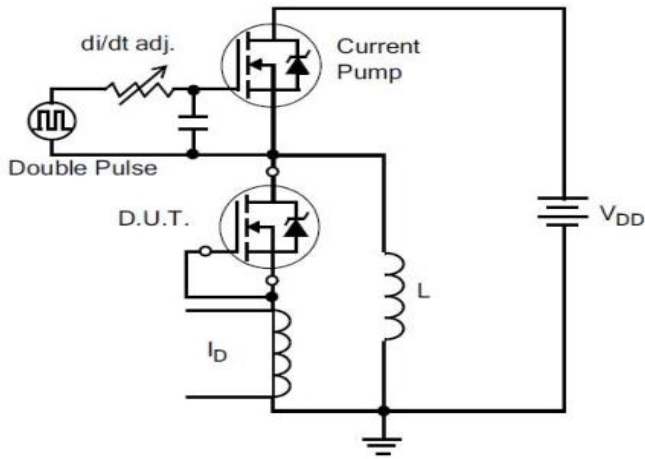


3) Resistive Switching Test Circuit

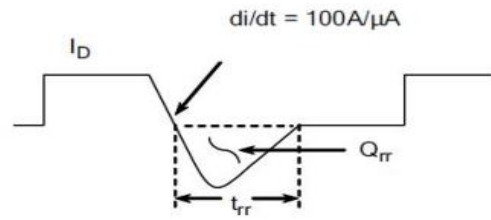


4) Resistive Switching Waveforms

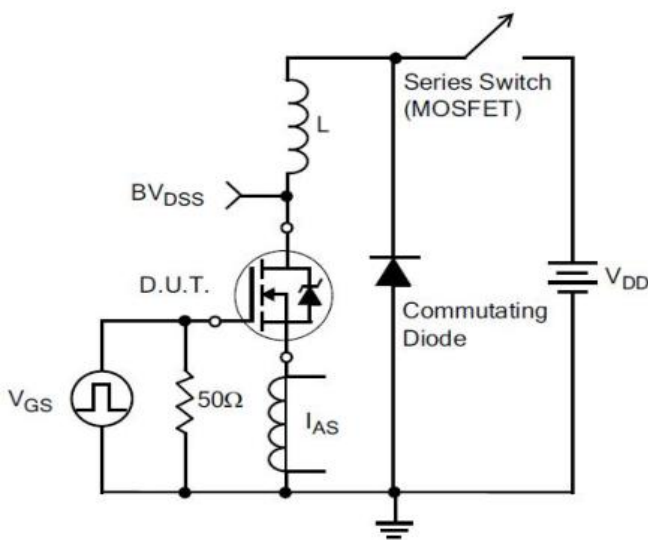
5 Typical Test Circuit and Waveform(continues)



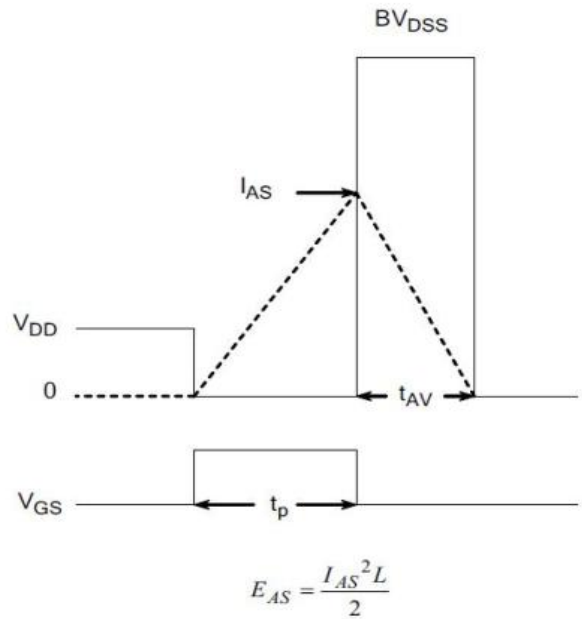
5) Diode Reverse Recovery Test Circuit



6) Diode Reverse Recovery Waveform

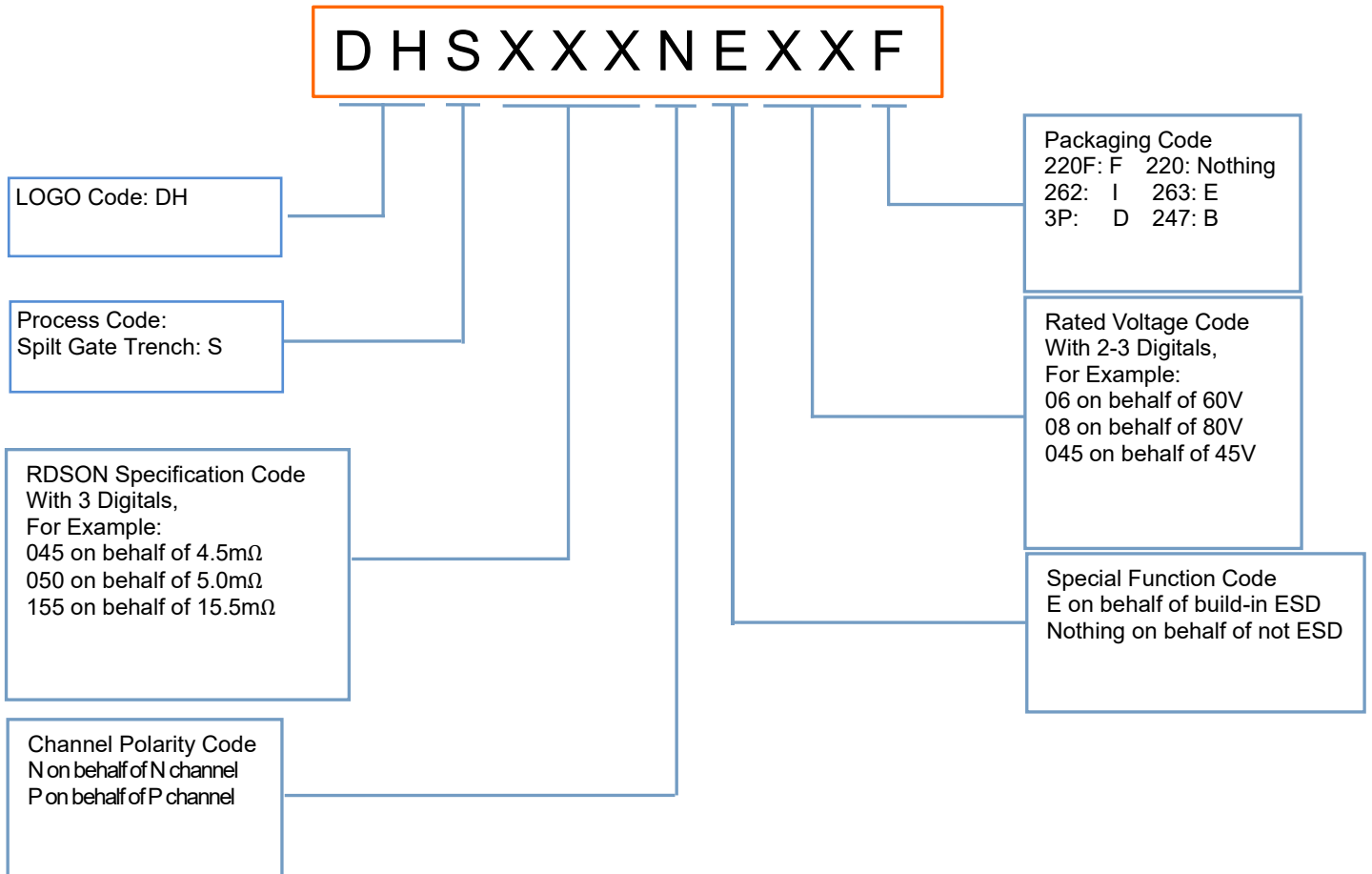


7) . Unclamped Inductive Switching Test Circuit



8) Unclamped Inductive Switching Waveforms

6 Product Names Rules

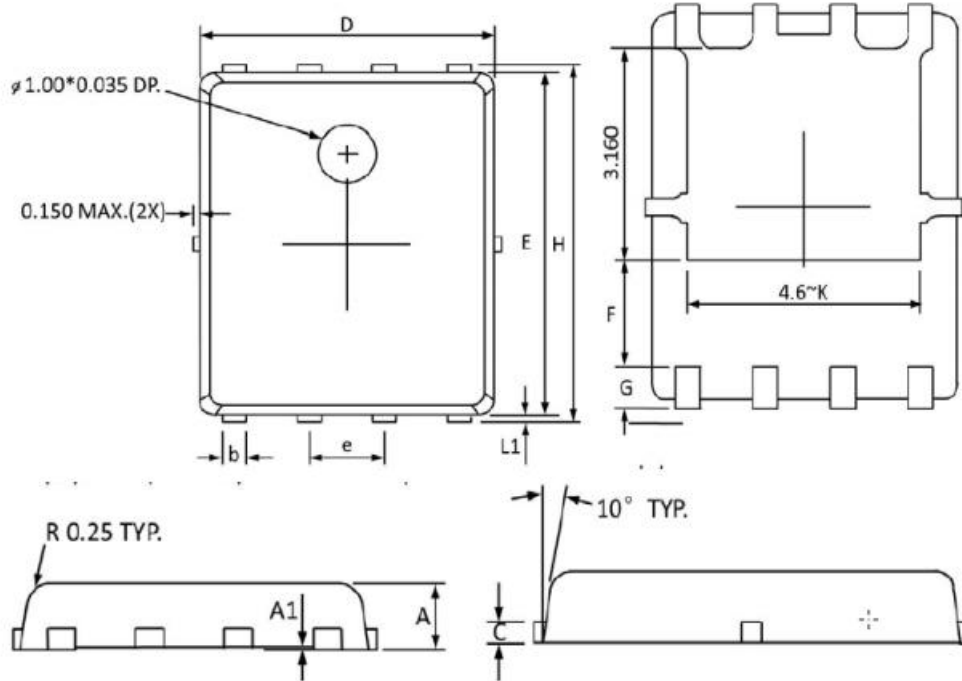


7 Product Specifications and Packaging Models

| Product Model | Package Type | Mark Name | RoHS | Package | Quantity |
|---------------|--------------|------------|---------|-------------|----------|
| DHS043N85P | DFN5*6-8 | DHS043N85P | Pb-free | Tape & Reel | 2500/box |

8 Dimensions

PPAK5x6 PACKAGE INFORMATION



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 0.800 | 1.000 | 0.032 | 0.039 |
| A1 | 0.000 | 0.005 | 0.000 | 0.000 |
| b | 0.350 | 0.490 | 0.014 | 0.019 |
| C | 0.254 Ref | | 0.254 Ref | |
| D | 4.900 | 5.100 | 0.193 | 0.200 |
| E | 5.700 | 5.900 | 0.225 | 0.232 |
| e | 1.27 BSC | | 1.27 BSC | |
| F | 1.600 Ref | | 1.600 Ref | |
| G | 0.600 Ref | | 0.600 Ref | |
| H | 5.950 | 6.200 | 0.235 | 0.244 |
| L1 | 0.100 | 0.180 | 0.004 | 0.007 |
| K | 3.200 Ref | | 3.200 Ref | |

9 Attentions

- Jiangsu Donghai Semiconductor Technology CO.,LTD. reserves the right to change the specification without prior notice! The customer should obtain the latest version of the information before making the order and verify that the information is complete and up to date.
- It is the responsibility of the purchaser for any failure or failure of any semiconductor product under certain conditions. It is the responsibility of the purchaser to comply with safety standards and to take safety measures in the system design and machine manufacturing of Donghai products in order to avoid potential risk of failure. Injury or property damage.
- Product promotion is endless, our company will be dedicated to provide customers with better products.

10 Appendix

Revision history:

| Date | REV. | Description | Page |
|------------|------|-------------|------|
| 2021.07.19 | 1.0 | Original | |